



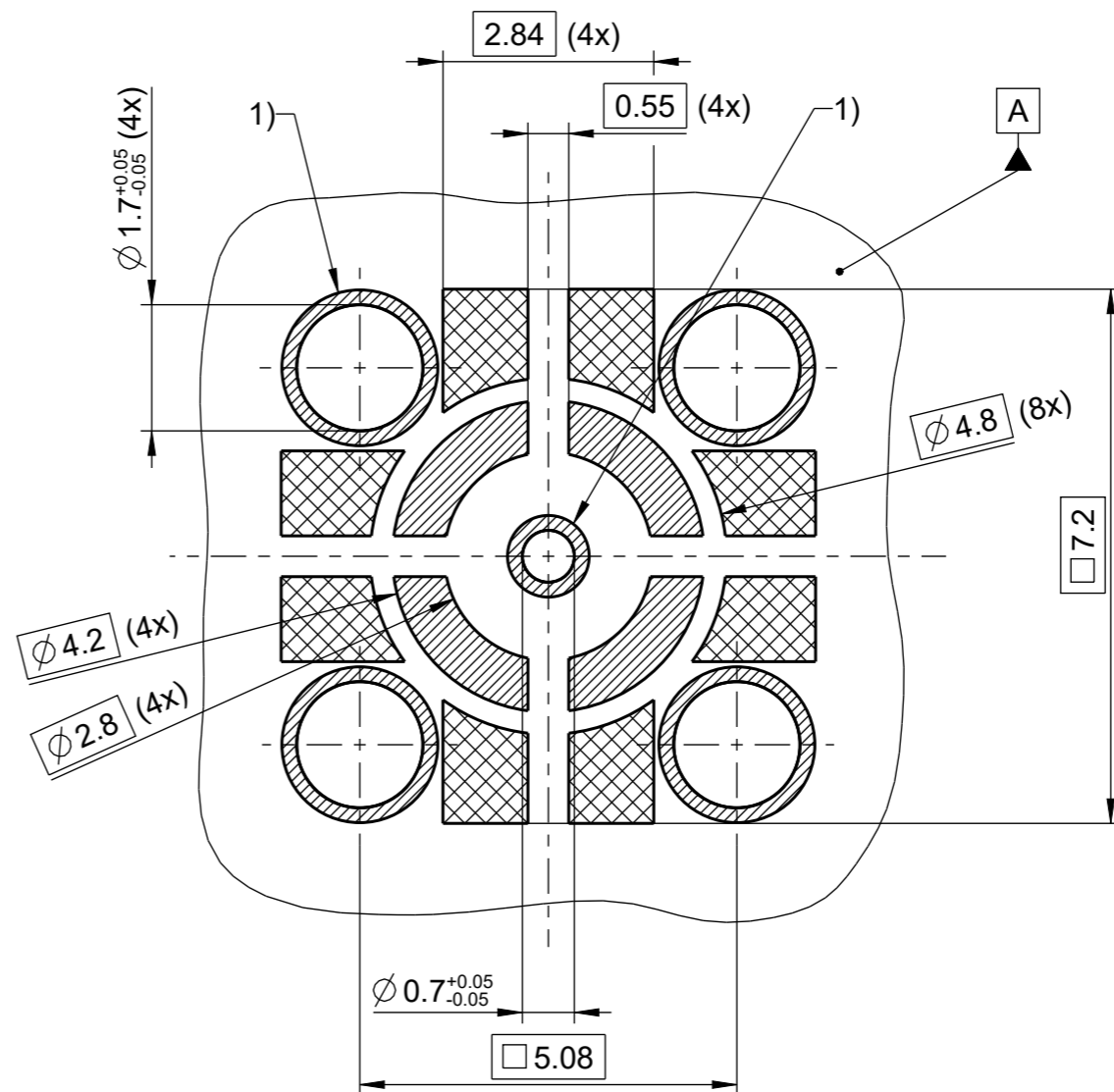
- 1) Pad width 0.2mm min.
- 2) Thickness of soldering paste 0.1mm min.
- 3) All through holes plated inclusive pads on backside

- 4) All through holes  $\text{⌀} 0.05 \text{ (M)} \text{ A}$

- 5) Solder area and keep out area  $\text{0.2 A B-B}$

 solder area (9x)

 keep out area, free of solder, no routing underneath (8x)



The stated dimensions are only recommendations.

A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimal solderability of the connector.

In order to guarantee optimal high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

<b>Rosenberger</b>		scale: 10:1		weight[g]:	
		material: ---		surface[mm <sup>2</sup> ]:	
<b>vertraulich / confidential</b>		drawn	01.03.2021	C_Zwinger	
		check.	02.03.2021	B_Krammer	
		appr.	08.03.2021	T_Georg	
		dimensioning incl. plating			
		Size ISO 14405 (E)		Leiterplatten-Layout PCB layout	
		Tolerancing ISO 8015			
100	19-v540	C_Zwinger	02.03.2021	drawing-no.: MB_926	
rev.	change-no	name	date	sheet: 1	
				of: 1	
remarks: .					